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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







2-Bit Dual-Supply Inverting Level Translator

The NLSV2T240 is a 2-bit configurable dual-supply voltage level translator. The input A_n and output B_n ports are designed to track two different power supply rails, $V_{\rm CCA}$ and $V_{\rm CCB}$ respectively. Both supply rails are configurable from 0.9 V to 4.5 V allowing universal low-voltage translation from the input A_n to the output B_n port.

Features

- Wide V_{CCA} and V_{CCB} Operating Range: 0.9 V to 4.5 V
- High-Speed w/ Balanced Propagation Delay
- Inputs and Outputs have OVT Protection to 4.5 V
- Non-preferential V_{CCA} and V_{CCB} Sequencing
- Outputs at 3-State until Active V_{CC} is Reached
- Power-Off Protection
- Outputs Switch to 3-State with V_{CCB} at GND
- Ultra-Small Packaging: 1.8 mm x 1.2 mm UDFN8
- This is a Pb-Free Device

Typical Applications

• Mobile Phones, PDAs, Other Portable Devices

Important Information

• ESD Protection for All Pins: HBM (Human Body Model) > 5000 V

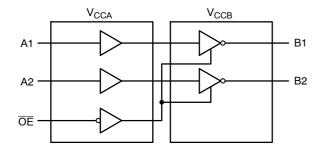


Figure 1. Logic Diagram



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MARKING DIAGRAM



VCM

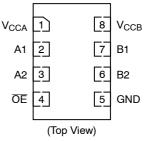
UDFN8 MU SUFFIX CASE 517AJ

VC = Specific Device Code

M = Date Code

= Pb-Free Package

PIN ASSIGNMENT



ORDERING INFORMATION

Device	Package	Shipping [†]
NLSV2T240MUTAG	UDFN8 (Pb-Free)	3000/Tape & Reel
	(Pb-Free)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

PIN ASSIGNMENT

PIN	FUNCTION
V _{CCA}	Input Port DC Power Supply
V _{CCB}	Output Port DC Power Supply
GND	Ground
A _n	Input Port
B _n	Output Port
ŌĒ	Output Enable

TRUTH TABLE

In	Outputs	
ŌĒ	A _n	B _n
L	L	Н
L	Н	L
Н	X	3-State

MAXIMUM RATINGS

Symbol	Rating		Value	Condition	Unit
V _{CCA} , V _{CCB}	DC Supply Voltage		-0.5 to +5.5		V
VI	DC Input Voltage	An	-0.5 to +5.5		V
V _C	Control Input	ΟE	-0.5 to +5.5		V
V _O	DC Output Voltage (Power Down)	B _n	-0.5 to +5.5	V _{CCA} = V _{CCB} = 0	V
	(Active Mode)	B _n	-0.5 to +5.5		V
	(Tri-State Mode)	B _n	-0.5 to +5.5		V
I _{IK}	DC Input Diode Current		-20	V _I < GND	mA
I _{OK}	DC Output Diode Current		-50	V _O < GND	mA
I _O	DC Output Source/Sink Current		±50		mA
I _{CCA} , I _{CCB}	DC Supply Current Per Supply Pin		±100		mA
I _{GND}	DC Ground Current per Ground Pin		±100		mA
T _{STG}	Storage Temperature		-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V _{CCA} , V _{CCB}	Positive DC Supply Voltage		0.9	4.5	V
V _I	Bus Input Voltage		GND	4.5	V
V _C	Control Input	ŌĒ	GND	4.5	V
V _{IO}	Bus Output Voltage (Power Down Mode)	B _n	GND	4.5	V
	(Active Mode)	B _n	GND	V _{CCB}	V
	(Tri-State Mode)	B _n	GND	4.5	V
T _A	Operating Temperature Range		-40	+85	°C
Δt / ΔV	Input Transition Rise or Rate V _I , from 30% to 70% of V _{CC} ; V _{CC} = 3.3 V \pm 0.3 V		0	10	nS

DC ELECTRICAL CHARACTERISTICS

					-40°C to	0 +85°C	
Symbol	Parameter	Test Conditions	V _{CCA} (V)	V _{CCB} (V)	Min	Max	Uni
V _{IH}	Input HIGH Voltage		3.6 – 4.5	0.9 – 4.5	2.2	-	V
	(An, \overline{OE})		2.7 – 3.6		2.0	-	
			2.3 – 2.7		1.6	-	
			1.4 – 2.3		0.65 * V _{CCA}	-	
			0.9 – 1.4	1	0.9 * V _{CCA}	-	
V _{IL}	Input LOW Voltage		3.6 – 4.5	0.9 – 4.5	-	0.8	V
	(An, \overline{OE})		2.7 – 3.6	1	-	0.8	
			2.3 – 2.7	1	-	0.7	
			1.4 – 2.3	1	-	0.35 * V _{CCA}	
			0.9 – 1.4	1	-	0.1 * V _{CCA}	
V _{OH}	Output HIGH Voltage	$I_{OH} = -100 \mu A; V_I = V_{IL}$	0.9 – 4.5	0.9 – 4.5	V _{CCB} - 0.2	-	V
		$I_{OH} = -0.5 \text{ mA}; V_I = V_{IL}$	0.9	0.9	0.75 * V _{CCB}	-	
		$I_{OH} = -2 \text{ mA}; V_I = V_{IL}$	1.4	1.4	1.05	-	
		$I_{OH} = -6 \text{ mA}; V_I = V_{IL}$	1.65	1.65	1.25	-	
			2.3	2.3	2.0	-	
		$I_{OH} = -12 \text{ mA}; V_I = V_{IL}$	2.3	2.3	1.8	-	
			2.7	2.7	2.2	-	
		$I_{OH} = -18 \text{ mA}; V_I = V_{IL}$	2.3	2.3	1.7	-	
			3.0	3.0	2.4	-	
		$I_{OH} = -24 \text{ mA}; V_I = V_{IL}$	3.0	3.0	2.2	-	
V _{OL}	Output LOW Voltage	$I_{OL} = 100 \mu A; V_I = V_{IH}$	0.9 – 4.5	0.9 – 4.5	-	0.2	V
		I _{OL} = 0.5 mA; V _I = V _{IH}	1.1	1.1	-	0.3	
		I _{OL} = 2 mA; V _I = V _{IH}	1.4	1.4	-	0.35	
		I_{OL} = 6 mA; V_I = V_{IH}	1.65	1.65	-	0.3	
		I _{OL} = 12 mA; V _I = V _{IH}	2.3	2.3	-	0.4	
			2.7	2.7	-	0.4	
		I _{OL} = 18 mA; V _I = V _{IH}	2.3	2.3	-	0.6	
			3.0	3.0	-	0.4	
		I _{OL} = 24 mA; V _I = V _{IH}	3.0	3.0	-	0.55	
II	Input Leakage Current	V _I = V _{CCA} or GND	0.9 – 4.5	0.9 – 4.5	-1.0	1.0	μA
I _{OFF}	Power-Off Leakage Current	ŌĒ = 0 V	0 0.9 – 4.5	0.9 – 4.5 0	-1.0 -1.0	1.0 1.0	μÆ
I _{CCA}	Quiescent Supply Current	$V_I = V_{CCA}$ or GND; $I_O = 0$, $V_{CCA} = V_{CCB}$	0.9 – 4.5	0.9 – 4.5	-	1.0	μA
I _{CCB}	Quiescent Supply Current	$V_I = V_{CCA}$ or GND; $I_O = 0$, $V_{CCA} = V_{CCB}$	0.9 – 4.5	0.9 – 4.5	-	1.0	μA
CA + ICCB	Quiescent Supply Current	$V_I = V_{CCA}$ or GND; $I_O = 0$, $V_{CCA} = V_{CCB}$	0.9 – 4.5	0.9 – 4.5	-	2.0	μA
ΔI_{CCA}	Increase in I_{CC} per Input Voltage, Other Inputs at V_{CCA} or GND	$V_I = V_{CCA} - 0.6 \text{ V};$ $V_I = V_{CCA} \text{ or GND}$	4.5 3.6	4.5 3.6	-	10 5.0	μA
ΔI_{CCB}	Increase in I_{CC} per Input Voltage, Other Inputs at V_{CCA} or GND	$V_I = V_{CCA} - 0.6 \text{ V};$ $V_I = V_{CCA} \text{ or GND}$	4.5 3.6	4.5 3.6	-	10 5.0	μA
l _{OZ}	I/O Tri-State Output Leakage	$T_A = 25^{\circ}C, \overline{OE} = 0 \text{ V}$	0.9 – 4.5	0.9 – 4.5	-1.0	1.0	μA

TOTAL STATIC POWER CONSUMPTION (I_{CCA} + I_{CCB})

					-40°C to	o +85°C					
	V _{CCB} (V)										
	4	.5	3.	.3	2.	.8	1.	8	0.	.9	
V _{CCA} (V)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
4.5		2		2		2		2		< 1.5	μΑ
3.3		2		2		2		2		< 1.5	μΑ
2.8		< 2		< 1		< 1		< 0.5		< 0.5	μΑ
1.8		< 1		< 1		< 0.5		< 0.5		< 0.5	μΑ
0.9		< 0.5		< 0.5		< 0.5		< 0.5		< 0.5	μΑ

 $NOTE: Connect ground before applying supply voltage \ V_{CCB}. This device is designed with the feature that the power-up sequence$ of V_{CCA} and V_{CCB} will not damage the IC.

AC ELECTRICAL CHARACTERISTICS

							-40°C t	o +85°C					
							V _{CC}	_B (V)					
			4	.5	3	.3	2	.8	1	.8	1.	2	
Symbol	Parameter	V _{CCA} (V)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Propagation	4.5		1.6		1.8		2.0		2.1		2.3	nS
t _{PHL}	Delay,	3.3		1.7		1.9		2.1		2.3		2.6	
(Note 1)	A _n to B _n	2.8		1.9		2.1		2.3		2.5		2.8	
		1.8		2.1		2.4		2.5		2.7		3.0	
		1.2		2.4		2.7		2.8		3.0		3.3	
t _{PZH} ,	Output	4.5		2.6		3.8		4.0		4.1		4.3	nS
t _{PZL}	Enable,	3.3		3.7		3.9		4.1		4.3		4.6	
(Note 1)	OE to B _n	2.5		3.9		4.1		4.3		4.5		4.8	
		1.8		4.1		4.4		4.5		4.7		5.0	
		1.2		4.4		4.7		4.8		5.0		5.3	
t _{PHZ} ,	Output	4.5		2.6		3.8		4.0		4.1		4.3	nS
t _{PLZ}	Disable,	3.3		3.7		3.9		4.1		4.3		4.6	
(Note 1)	OE to B _n	2.5		3.9		4.1		4.3		4.5		4.8	
		1.8		4.1		4.4		4.5		4.7		5.0	
		1.2		4.4		4.7		4.8		5.0		5.3	
t _{OSHL} ,	Output to	4.5		0.15		0.15		0.15		0.15		0.15	nS
t _{OSLH}	Output Skew,	3.3		0.15		0.15		0.15		0.15		0.15	
(Note 1)	Time	2.5		0.15		0.15		0.15		0.15		0.15	
		1.8		0.15		0.15		0.15		0.15		0.15	
		1.2		0.15		0.15		0.15		0.15		0.15	

^{1.} Propagation delays defined per Figure 2.

CAPACITANCE

Symbol	Parameter	Test Conditions	Typ (Note 2)	Unit
C _{IN}	Control Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CCA/B}$	3.5	pF
C _{I/O}	I/O Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CCA/B}$	5.0	pF
C _{PD}	Power Dissipation Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_{I} = 0 \text{ V or } V_{CCA}, f = 10 \text{ MHz}$	20	pF

Typical values are at T_A = +25°C.
 C_{PD} is defined as the value of the IC's equivalent capacitance from which the operating current can be calculated from: I_{CC(operating)} ≅ C_{PD} x V_{CC} x f_{IN} x N_{SW} where I_{CC} = I_{CCA} + I_{CCB} and N_{SW} = total number of outputs switching.

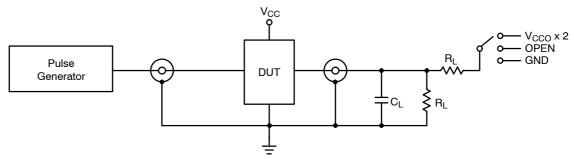


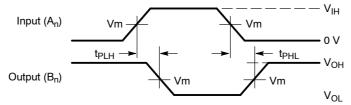
Figure 2. AC (Propagation Delay) Test Circuit

Test	Switch
t _{PLH} , t _{PHL}	OPEN
t _{PLZ} , t _{PZL}	V _{CCO} x 2
t _{PHZ} , t _{PZH}	GND

C_L = 15 pF or equivalent (includes probe and jig capacitance)

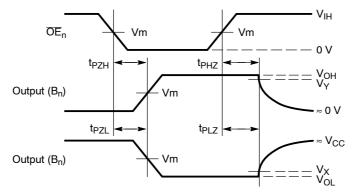
 $R_L = 2 k\Omega$ or equivalent

 Z_{OUT} of pulse generator = 50 Ω



Waveform 1 - Propagation Delays

 $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$



Waveform 2 - Output Enable and Disable Times

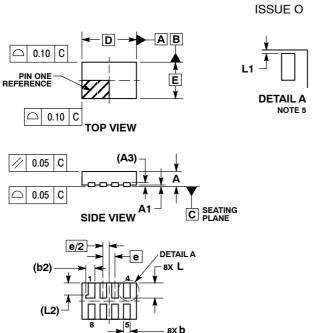
 t_{R} = t_{F} = 2.0 ns, 10% to 90%; f = 1 MHz; t_{W} = 500 ns

Figure 3. AC (Propagation Delay) Test Circuit Waveforms

	V _{CC}						
Symbol	3.0 V – 4.5 V	2.3 V – 2.7 V	1.65 V – 1.95 V	1.4 V – 1.6 V	0.9 V – 1.3 V		
V _{mA}	V _{CCA} /2						
V _{mB}	V _{CCB} /2						
V _X	V _{OL} x 0.1						
V _Y	V _{OH} x 0.9						

PACKAGE DIMENSIONS

UDFN8 1.8 x 1.2, 0.4P CASE 517AJ



BOTTOM VIEW

0.10 M C A B

0.05 M C NOTE 3

NOTES:

- NOTES:

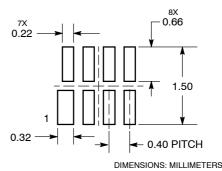
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION b APPLIES TO PLATED
- TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
- MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH MAY NOT EXCEED 0.03 ONTO BOTTOM SURFACE OF TERMINALS.
- **DETAIL A SHOWS OPTIONAL** CONSTRUCTION FOR TERMINALS

	MILLIMETERS					
DIM	MIN	MAX				
Α	0.45	0.55				
A1	0.00	0.05				
А3	0.127	REF				
b	0.15	0.25				
b2	0.30	REF				
D	1.80	BSC				
E	1.20	BSC				
е	0.40	BSC				
L	0.45	0.55				
L1	0.00	0.03				
L2	0.40	REF				

MOUNTING FOOTPRINT **SOLDERMASK DEFINED**



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